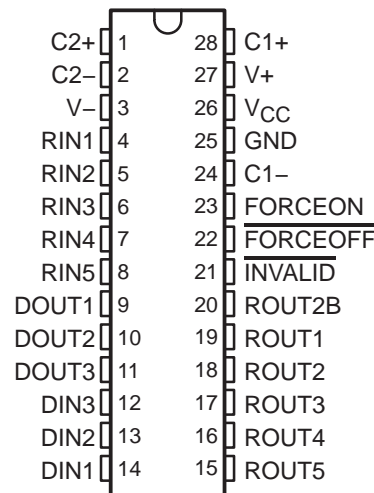


3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ± 15 -kV ESD (HBM) PROTECTION

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- **Single-Chip and Single-Supply Interface for IBM™ PC/AT™ Serial Port**
- **RS-232 Bus-Pin ESD Protection Exceeds ± 15 kV Using Human-Body Model (HBM)**
- **Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards**
- **Operates With 3-V to 5.5-V V_{CC} Supply**
- **Three Drivers and Five Receivers**
- **Operates Up To 250 kbit/s**
- **Designed to Transmit at a Data Rate of 250 kbit/s**
- **Low Standby Current . . . 1 μ A Typical**
- **External Capacitors . . . $4 \times 0.1 \mu$ F**
- **Accepts 5-V Logic Input With 3.3-V Supply**
- **Always-Active Noninverting Receiver Output (ROUT2B)**
- **Alternative High-Speed Pin-Compatible Device (1 Mbit/s)**
 - SNx5C3243
- **Serial-Mouse Driveability**
- **Auto-Powerdown Feature to Disable Driver Outputs When No Valid RS-232 Signal Is Sensed**
- **Applications**
 - Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and Hand-Held Equipment

DB, DW, OR PW PACKAGE
(TOP VIEW)



description/ordering information

The MAX3243 consists of three line drivers, five line receivers, and a dual charge-pump circuit with ± 15 -kV ESD (HBM) protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. This combination of drivers and receivers matches that needed for the typical serial port used in an IBM PC/AT, or compatible. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, the device includes an always-active noninverting output (ROUT2B), which allows applications using the ring indicator to transmit data while the device is powered down. The device operates at data signaling rates up to 250 kbit/s and a maximum of 30-V/ μ s driver output slew rate.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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MAX3243

3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

WITH ± 15 -kV ESD (HBM) PROTECTION

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description/ordering information (continued)

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and $\overline{\text{FORCEOFF}}$ is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If $\overline{\text{FORCEOFF}}$ is set low, both drivers and receivers (except ROUT2B) are shut off, and the supply current is reduced to 1 μA . Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur.

Auto-powerdown can be disabled when FORCEON and $\overline{\text{FORCEOFF}}$ are high and should be done when driving a serial mouse. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The INVALID output is used to notify the user if an RS-232 signal is present at any receiver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V or has been between -0.3 V and 0.3 V for less than 30 μs . INVALID is low (invalid data) if all receiver input voltages are between -0.3 V and 0.3 V for more than 30 μs . Refer to Figure 5 for receiver input levels.

ORDERING INFORMATION

| TA | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---------------|------------|--------------|-----------------------|------------------|
| 0°C to 70°C | SOIC (DW) | Tube of 20 | MAX3243CDW | MAX3243C |
| | | Reel of 1000 | MAX3243CDWR | |
| | SSOP (DB) | Tube of 50 | MAX3243CDB | MAX3243C |
| | | Reel of 2000 | MAX3243CDBR | |
| | TSSOP (PW) | Tube of 50 | MAX3243CPW | MA3243C |
| | | Reel of 2000 | MAX3243CPWR | |
| -40°C to 85°C | SOIC (DW) | Tube of 20 | MAX3243IDW | MAX3243I |
| | | Reel of 1000 | MAX3243IDWR | |
| | SSOP (DB) | Tube of 50 | MAX3243IDB | MAX3243I |
| | | Reel of 2000 | MAX3243IDBR | |
| | TSSOP (PW) | Tube of 50 | MAX3243IPW | MB3243I |
| | | Reel of 2000 | MAX3243IPWR | |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Function Tables

EACH DRIVER

| INPUTS | | | | OUTPUT DOUT | DRIVER STATUS |
|--------|---------|------------------------------|------------------------|-------------|---|
| DIN | FORCEON | $\overline{\text{FORCEOFF}}$ | VALID RIN RS-232 LEVEL | | |
| X | X | L | X | Z | Powered off |
| L | H | H | X | H | Normal operation with auto-powerdown disabled |
| H | H | H | X | L | |
| L | L | H | Yes | H | Normal operation with auto-powerdown enabled |
| H | L | H | Yes | L | |
| L | L | H | No | Z | Powered off by auto-powerdown feature |
| H | L | H | No | Z | |

H = high level, L = low level, X = irrelevant, Z = high impedance



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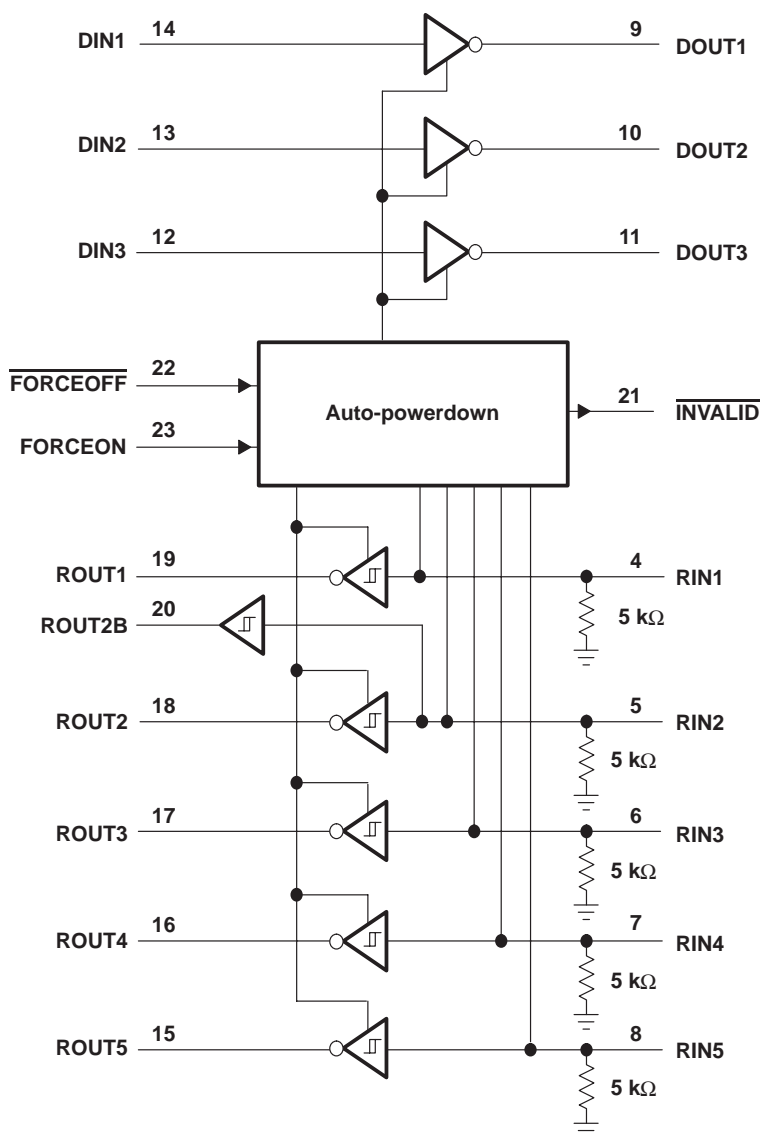
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EACH RECEIVER

| INPUTS | | | | OUTPUTS | | RECEIVER STATUS |
|--------|--------------------|------------------------------|---------------------------|---------|------|---|
| RIN2 | RIN1, RIN3-RIN5 | $\overline{\text{FORCEOFF}}$ | VALID RIN RS-232 LEVEL | ROUT2B | ROUT | |
| L | X | L | X | L | Z | Powered off while ROUT2B is active |
| H | X | L | X | H | Z | |
| L | L | H | Yes | L | H | Normal operation with auto-powerdown disabled/enabled |
| L | H | H | Yes | L | L | |
| H | L | H | Yes | H | H | |
| H | H | H | Yes | H | L | |
| Open | Open | H | No | L | H | |

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

logic diagram (positive logic)



MAX3243
3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER
WITH ±15-kV ESD (HBM) PROTECTION

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|---|----------------------------|
| Supply voltage range, V_{CC} (see Note 1) | –0.3 V to 6 V |
| Positive output supply voltage range, $V+$ (see Note 1) | –0.3 V to 7 V |
| Negative output supply voltage range, $V-$ (see Note 1) | 0.3 V to –7 V |
| Supply voltage difference, $V+ - V-$ (see Note 1) | 13 V |
| Input voltage range, V_I : Driver ($\overline{\text{FORCEOFF}}$, FORCEON) | –0.3 V to 6 V |
| Receiver | –25 V to 25 V |
| Output voltage range, V_O : Driver | –13.2 V to 13.2 V |
| Receiver (INVALID) | –0.3 V to $V_{CC} + 0.3$ V |
| Package thermal impedance, θ_{JA} (see Notes 2 and 3): DB package | 62°C/W |
| DW package | 46°C/W |
| PW package | 62°C/W |
| Operating virtual junction temperature, T_J | 150°C |
| Storage temperature range, T_{stg} | –65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
2. Maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_{J(max)} - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 6)

| | | | MIN | NOM | MAX | UNIT |
|----------------|---|---|------------------|-----|-----|------|
| Supply voltage | | $V_{CC} = 3.3$ V | 3 | 3.3 | 3.6 | V |
| | | $V_{CC} = 5$ V | 4.5 | 5 | 5.5 | |
| V_{IH} | Driver and control high-level input voltage | DIN, $\overline{\text{FORCEOFF}}$, FORCEON | $V_{CC} = 3.3$ V | 2 | | V |
| | | | $V_{CC} = 5$ V | 2.4 | | |
| V_{IL} | Driver and control low-level input voltage | DIN, $\overline{\text{FORCEOFF}}$, FORCEON | | | 0.8 | V |
| V_I | Driver and control input voltage | DIN, $\overline{\text{FORCEOFF}}$, FORCEON | 0 | 5.5 | | V |
| V_I | Receiver input voltage | | –25 | 25 | | V |
| T_A | Operating free-air temperature | MAX3243C | 0 | 70 | | °C |
| | | MAX3243I | –40 | 85 | | |

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at $V_{CC} = 3.3$ V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at $V_{CC} = 5$ V \pm 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

| PARAMETER | | TEST CONDITIONS | | MIN | TYP‡ | MAX | UNIT |
|-----------|-----------------------|--|--|-----|------------|---------|---------|
| I_I | Input leakage current | $\overline{\text{FORCEOFF}}$, FORCEON | | | ± 0.01 | ± 1 | μ A |
| I_{CC} | Supply current | Auto-powerdown disabled | No load, $\overline{\text{FORCEOFF}}$ and FORCEON at V_{CC} | | 0.3 | 1 | mA |
| | | Powered off | $V_{CC} = 3.3$ V or 5 V, $T_A = 25^\circ\text{C}$ | | 1 | 10 | |
| | | Auto-powerdown enabled | No load, $\overline{\text{FORCEOFF}}$ at V_{CC} , FORCEON at GND, All RIN are open or grounded, All DIN are grounded | | 1 | 10 | μ A |

‡ All typical values are at $V_{CC} = 3.3$ V or $V_{CC} = 5$ V, and $T_A = 25^\circ\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at $V_{CC} = 3.3$ V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at $V_{CC} = 5$ V \pm 0.5 V.



MAX3243
3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER
WITH ±15-kV ESD (HBM) PROTECTION

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DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

| PARAMETER | | TEST CONDITIONS | MIN | TYP† | MAX | UNIT |
|------------------|-------------------------------------|---|-----|-------|------------|------|
| V _{OH} | High-level output voltage | All DOUT at R _L = 3 kΩ to GND | 5 | 5.4 | | V |
| V _{OL} | Low-level output voltage | All DOUT at R _L = 3 kΩ to GND | -5 | -5.4 | | V |
| V _O | Output voltage (mouse driveability) | DIN1 = DIN2 = GND, DIN3 = V _{CC} , 3-kΩ to GND at DOUT3, DOUT1 = DOUT2 = 2.5 mA | ±5 | | | V |
| I _{IH} | High-level input current | V _I = V _{CC} | | ±0.01 | ±1 | μA |
| I _{IL} | Low-level input current | V _I at GND | | ±0.01 | ±1 | μA |
| I _{OS} | Short-circuit output current‡ | V _{CC} = 3.6 V, V _O = 0 V V _{CC} = 5.5 V, V _O = 0 V | | ±35 | ±60 | mA |
| r _o | Output resistance | V _{CC} , V+, and V- = 0 V, V _O = ±2 V | 300 | 10M | | Ω |
| I _{off} | Output leakage current | $\overline{\text{FORCEOFF}} = \text{GND}$ V _O = ±12 V, V _{CC} = 3 V to 3.6 V V _O = ±10 V, V _{CC} = 4.5 V to 5.5 V | | | ±25 ±25 | μA |

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

‡ Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Test conditions are C1–C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

| PARAMETER | | TEST CONDITIONS | MIN | TYP† | MAX | UNIT |
|--------------------|---|--|-----|------|-----|--------|
| Maximum data rate | | C _L = 1000 pF, One DOUT switching, R _L = 3 kΩ, See Figure 1 | 150 | 250 | | kbit/s |
| t _{sk(p)} | Pulse skew§ | C _L = 150 pF to 2500 pF, R _L = 3 kΩ to 7 kΩ, See Figure 2 | | 100 | | ns |
| SR(tr) | Slew rate, transition region (see Figure 1) | V _{CC} = 3.3 V, R _L = 3 kΩ to 7 kΩ, C _L = 150 pF to 1000 pF | 6 | | 30 | V/μs |
| | | C _L = 150 pF to 2500 pF | 4 | | 30 | |

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

§ Pulse skew is defined as |t_{pLH} - t_{pHL}| of each channel of the same device.

NOTE 4: Test conditions are C1–C4 = 0.1 μF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μF, C2–C4 = 0.33 μF at V_{CC} = 5 V ± 0.5 V.

MAX3243**3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER
WITH ± 15 -kV ESD (HBM) PROTECTION**

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RECEIVER SECTION**electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)**

| PARAMETER | | TEST CONDITIONS | MIN | TYP† | MAX | UNIT |
|------------------|---|--------------------------------|------------------------|------------------------|-----|------|
| V _{OH} | High-level output voltage | I _{OH} = -1 mA | V _{CC} -0.6 V | V _{CC} -0.1 V | | V |
| V _{OL} | Low-level output voltage | I _{OL} = 1.6 mA | | | 0.4 | V |
| V _{IT+} | Positive-going input threshold voltage | V _{CC} = 3.3 V | | 1.6 | 2.4 | V |
| | | V _{CC} = 5 V | | 1.9 | 2.4 | |
| V _{IT-} | Negative-going input threshold voltage | V _{CC} = 3.3 V | 0.6 | 1.1 | | V |
| | | V _{CC} = 5 V | 0.8 | 1.4 | | |
| V _{hys} | Input hysteresis (V _{IT+} - V _{IT-}) | | | 0.5 | | V |
| I _{off} | Output leakage current (except ROUT2B) | FORCEOFF = 0 V | | ±0.05 | ±10 | µA |
| r _i | Input resistance | V _I = ±3 V to ±25 V | 3 | 5 | 7 | kΩ |

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.NOTE 4: Test conditions are C1-C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2-C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.**switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)**

| PARAMETER | | TEST CONDITIONS | MIN | TYP† | MAX | UNIT |
|--------------------|---|--|-----|------|-----|------|
| t _{PLH} | Propagation delay time, low- to high-level output | C _L = 150 pF, See Figure 3 | | 150 | | ns |
| t _{PHL} | Propagation delay time, high- to low-level output | | | | 150 | |
| t _{en} | Output enable time | C _L = 150 pF, R _L = 3 kΩ, See Figure 4 | | 200 | | ns |
| t _{dis} | Output disable time | | | | 200 | |
| t _{sk(p)} | Pulse skew‡ | See Figure 3 | | 50 | | ns |

† All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.‡ Pulse skew is defined as |t_{PLH} - t_{PHL}| of each channel of the same device.NOTE 4: Test conditions are C1-C4 = 0.1 µF at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 µF, C2-C4 = 0.33 µF at V_{CC} = 5 V ± 0.5 V.

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3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER
WITH ±15-kV ESD (HBM) PROTECTION

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AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

| PARAMETER | | TEST CONDITIONS | MIN | TYP† | MAX | UNIT |
|-------------------------|--|---|--------------|------|-----|------|
| $V_{T+}(\text{valid})$ | Receiver input threshold for INVALID high-level output voltage | $\overline{\text{FORCEON}} = \text{GND}$, $\overline{\text{FORCEOFF}} = V_{CC}$ | | | 2.7 | V |
| $V_{T-}(\text{valid})$ | Receiver input threshold for INVALID high-level output voltage | $\overline{\text{FORCEON}} = \text{GND}$, $\overline{\text{FORCEOFF}} = V_{CC}$ | -2.7 | | | V |
| $V_{T}(\text{invalid})$ | Receiver input threshold for INVALID low-level output voltage | $\overline{\text{FORCEON}} = \text{GND}$, $\overline{\text{FORCEOFF}} = V_{CC}$ | -0.3 | | 0.3 | V |
| V_{OH} | $\overline{\text{INVALID}}$ high-level output voltage | $I_{OH} = -1 \text{ mA}$, $\overline{\text{FORCEON}} = \text{GND}$, $\overline{\text{FORCEOFF}} = V_{CC}$ | $V_{CC}-0.6$ | | | V |
| V_{OL} | $\overline{\text{INVALID}}$ low-level output voltage | $I_{OL} = 1.6 \text{ mA}$, $\overline{\text{FORCEON}} = \text{GND}$, $\overline{\text{FORCEOFF}} = V_{CC}$ | | | 0.4 | V |

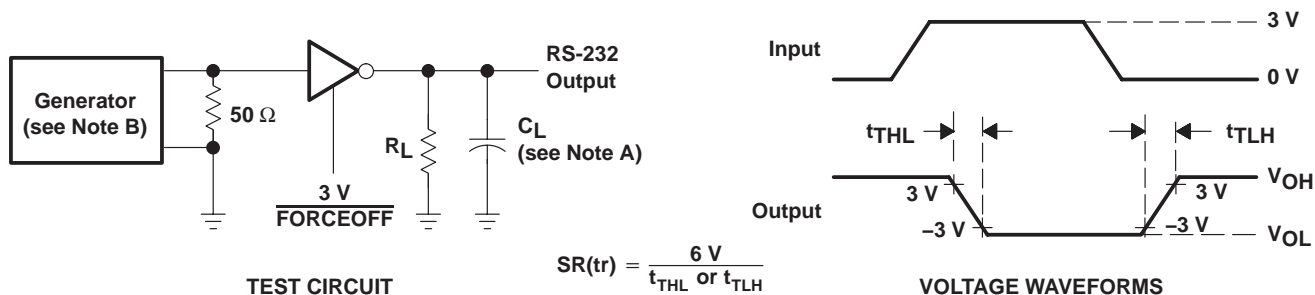
† All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^\circ\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

| PARAMETER | | MIN | TYP† | MAX | UNIT |
|----------------------|---|-----|------|-----|---------------|
| t_{valid} | Propagation delay time, low- to high-level output | | 1 | | μs |
| t_{invalid} | Propagation delay time, high- to low-level output | | 30 | | μs |
| t_{en} | Supply enable time | | 100 | | μs |

† All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^\circ\text{C}$.

PARAMETER MEASUREMENT INFORMATION



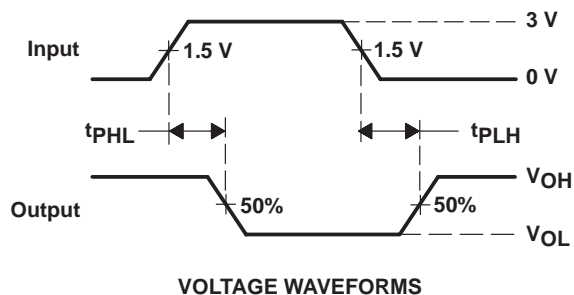
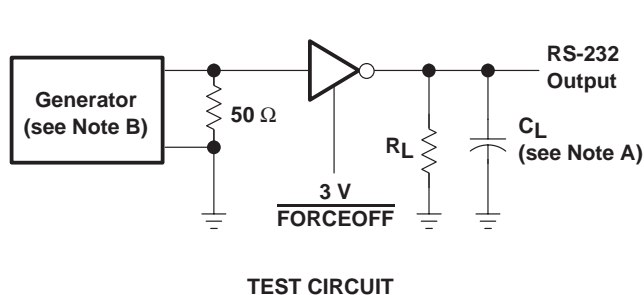
- NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$.

Figure 1. Driver Slew Rate

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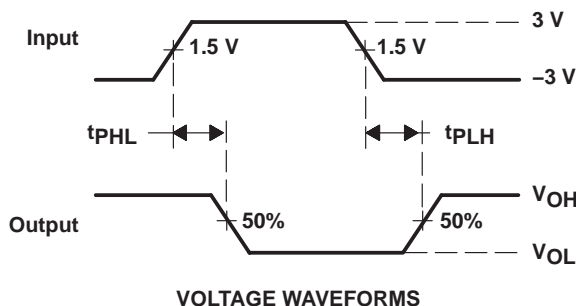
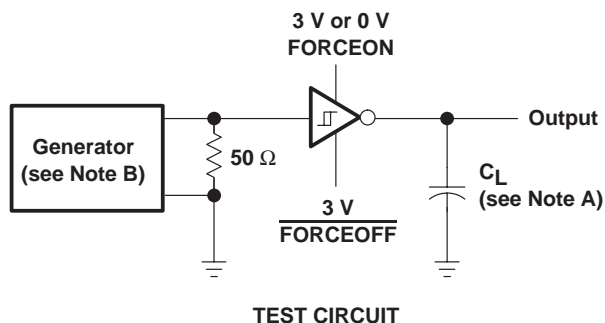
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PARAMETER MEASUREMENT INFORMATION



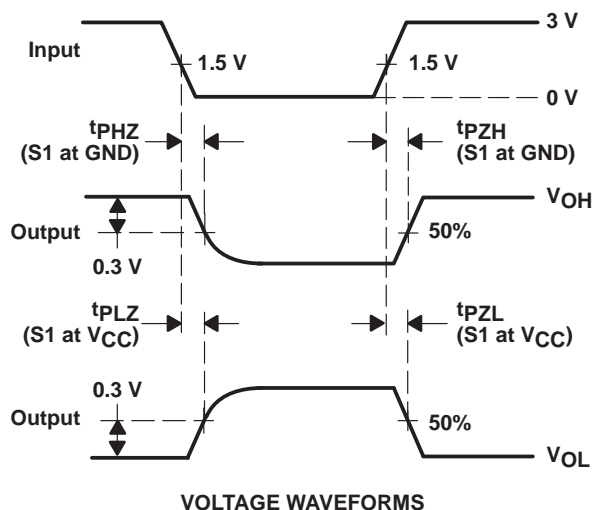
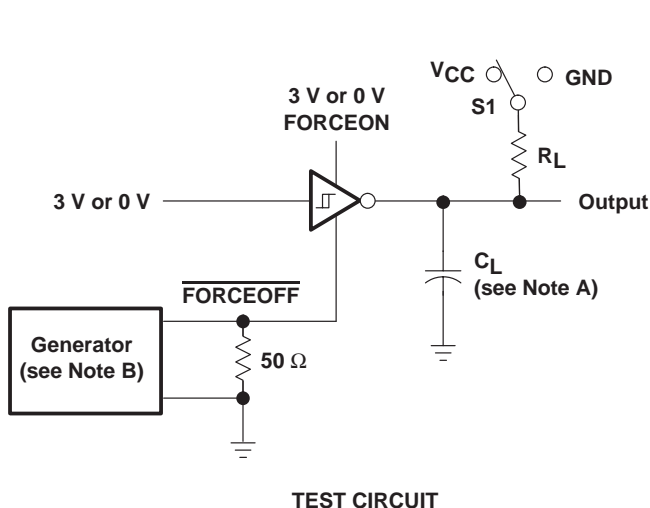
NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 2. Driver Pulse Skew



NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 3. Receiver Propagation Delay Times



NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.
 C. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 D. t_{PZL} and t_{PZH} are the same as t_{en} .

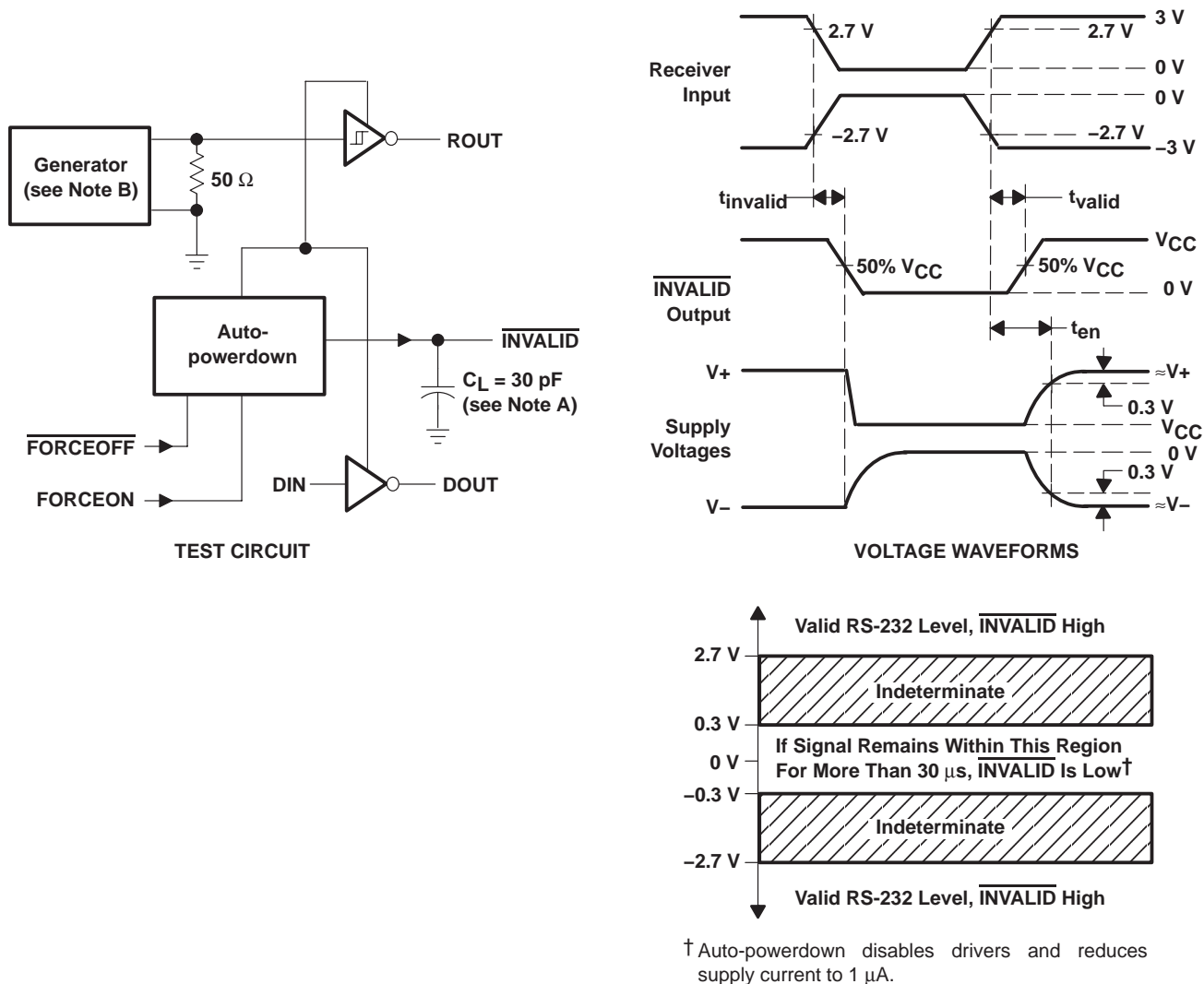
Figure 4. Receiver Enable and Disable Times



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PARAMETER MEASUREMENT INFORMATION



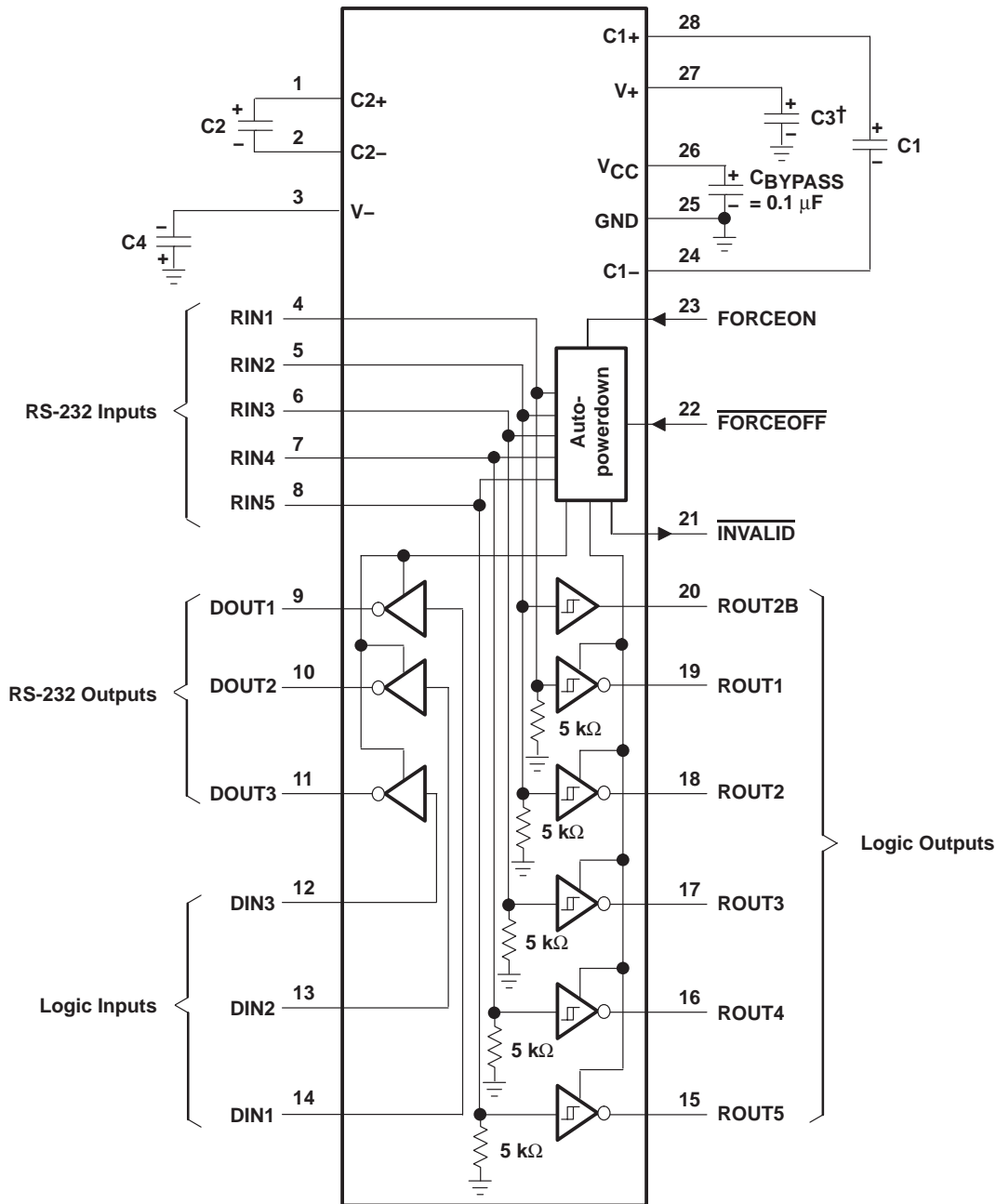
NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.

Figure 5. $\overline{\text{INVALID}}$ Propagation Delay Times and Supply Enabling Time

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3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER
WITH ±15-kV ESD (HBM) PROTECTION

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APPLICATION INFORMATION



† C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

| V _{CC} | C1 | C2, C3, and C4 |
|-----------------|----------|----------------|
| 3.3 V ± 0.3 V | 0.1 μF | 0.1 μF |
| 5 V ± 0.5 V | 0.047 μF | 0.33 μF |
| 3 V to 5.5 V | 0.1 μF | 0.47 μF |

Figure 6. Typical Operating Circuit and Capacitor Values



PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| MAX3243CDB | ACTIVE | SSOP | DB | 28 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CDBE4 | ACTIVE | SSOP | DB | 28 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CDBG4 | ACTIVE | SSOP | DB | 28 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CDBR | ACTIVE | SSOP | DB | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CDBRE4 | ACTIVE | SSOP | DB | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CDBRG4 | ACTIVE | SSOP | DB | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CDW | ACTIVE | SOIC | DW | 28 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CDWE4 | ACTIVE | SOIC | DW | 28 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CDWG4 | ACTIVE | SOIC | DW | 28 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CDWR | ACTIVE | SOIC | DW | 28 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CDWRG4 | ACTIVE | SOIC | DW | 28 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CPW | ACTIVE | TSSOP | PW | 28 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CPWE4 | ACTIVE | TSSOP | PW | 28 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CPWG4 | ACTIVE | TSSOP | PW | 28 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CPWR | ACTIVE | TSSOP | PW | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CPWRE4 | ACTIVE | TSSOP | PW | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243CPWRG4 | ACTIVE | TSSOP | PW | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IDB | ACTIVE | SSOP | DB | 28 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IDBE4 | ACTIVE | SSOP | DB | 28 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IDBG4 | ACTIVE | SSOP | DB | 28 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IDBR | ACTIVE | SSOP | DB | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IDBRE4 | ACTIVE | SSOP | DB | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IDBRG4 | ACTIVE | SSOP | DB | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IDW | ACTIVE | SOIC | DW | 28 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IDWG4 | ACTIVE | SOIC | DW | 28 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| MAX3243IDWR | ACTIVE | SOIC | DW | 28 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IDWRE4 | ACTIVE | SOIC | DW | 28 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IDWRG4 | ACTIVE | SOIC | DW | 28 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IPW | ACTIVE | TSSOP | PW | 28 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IPWG4 | ACTIVE | TSSOP | PW | 28 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IPWR | ACTIVE | TSSOP | PW | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IPWRE4 | ACTIVE | TSSOP | PW | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| MAX3243IPWRG4 | ACTIVE | TSSOP | PW | 28 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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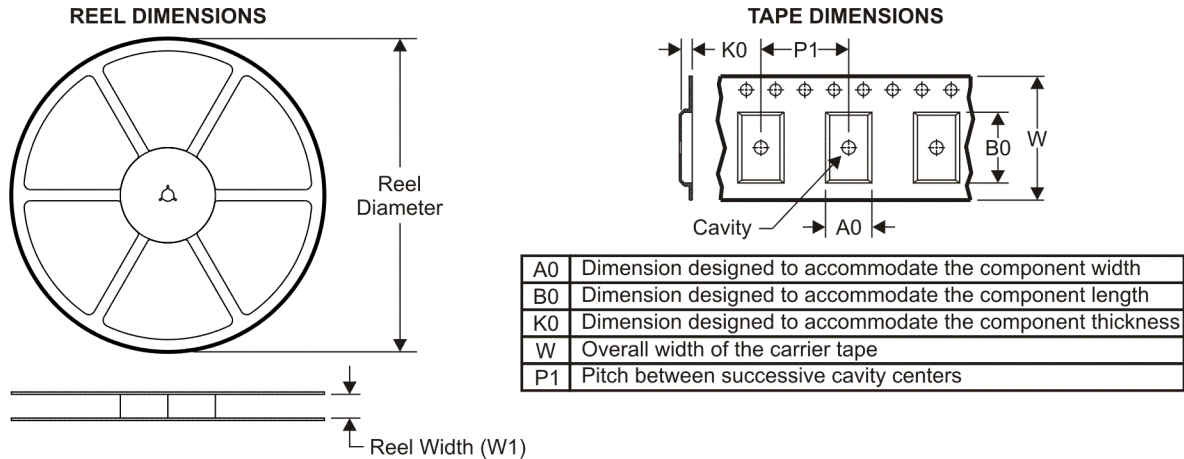
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OTHER QUALIFIED VERSIONS OF MAX3243 :

- Enhanced Product: [MAX3243-EP](#)

NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| MAX3243CDBR | SSOP | DB | 28 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| MAX3243CDWR | SOIC | DW | 28 | 1000 | 330.0 | 32.4 | 11.35 | 18.67 | 3.1 | 16.0 | 32.0 | Q1 |
| MAX3243CPWR | TSSOP | PW | 28 | 2000 | 330.0 | 16.4 | 6.9 | 10.2 | 1.8 | 12.0 | 16.0 | Q1 |
| MAX3243CPWR | TSSOP | PW | 28 | 2000 | 330.0 | 16.4 | 7.1 | 10.4 | 1.6 | 12.0 | 16.0 | Q1 |
| MAX3243IDBR | SSOP | DB | 28 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| MAX3243IDWR | SOIC | DW | 28 | 1000 | 330.0 | 32.4 | 11.35 | 18.67 | 3.1 | 16.0 | 32.0 | Q1 |
| MAX3243IPWR | TSSOP | PW | 28 | 2000 | 330.0 | 16.4 | 6.9 | 10.2 | 1.8 | 12.0 | 16.0 | Q1 |
| MAX3243IPWR | TSSOP | PW | 28 | 2000 | 330.0 | 16.4 | 7.1 | 10.4 | 1.6 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| MAX3243CDBR | SSOP | DB | 28 | 2000 | 346.0 | 346.0 | 33.0 |
| MAX3243CDWR | SOIC | DW | 28 | 1000 | 346.0 | 346.0 | 49.0 |
| MAX3243CPWR | TSSOP | PW | 28 | 2000 | 346.0 | 346.0 | 33.0 |
| MAX3243CPWR | TSSOP | PW | 28 | 2000 | 346.0 | 346.0 | 33.0 |
| MAX3243IDBR | SSOP | DB | 28 | 2000 | 346.0 | 346.0 | 33.0 |
| MAX3243IDWR | SOIC | DW | 28 | 1000 | 346.0 | 346.0 | 49.0 |
| MAX3243IPWR | TSSOP | PW | 28 | 2000 | 346.0 | 346.0 | 33.0 |
| MAX3243IPWR | TSSOP | PW | 28 | 2000 | 346.0 | 346.0 | 33.0 |

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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